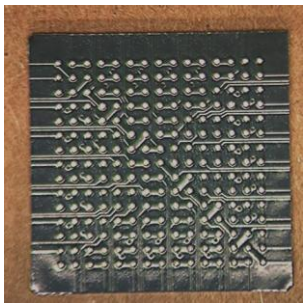
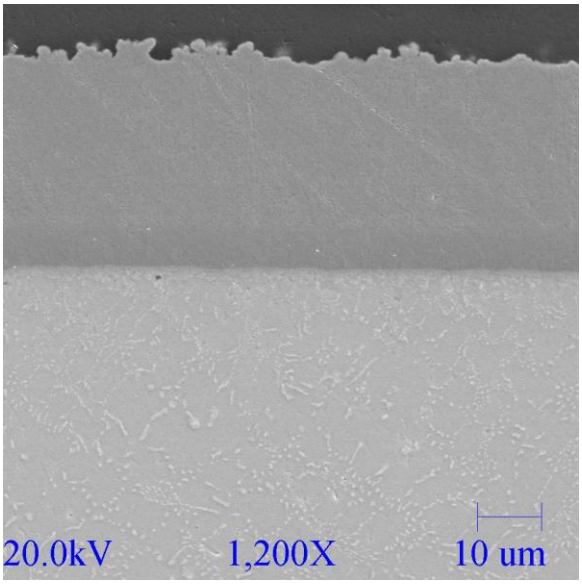
Package Characteristics: BGA Pbfree

Top View

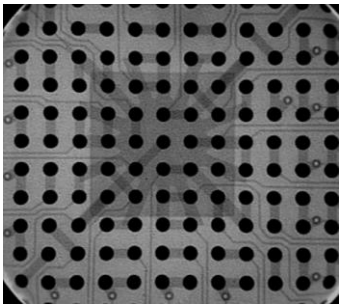

Bottom View

Feature	Value
Package Length	27.05 mm
Package Width	26.96 mm
Package Thickness	1.71 mm
Diameter of Solder Balls	0.78 mm
Die Length	8.74 mm
Die Width	8.80 mm
Die Thickness	0.30 mm
Pitch	1.49 mm
Weight	2.34 g
CTE	12.35 ppm/C
Width of Solder ball in contact with component pad	0.598 mm
Solderball Alloy (SEM estimate)	Sn3.5Ag0.9Cu

Cross-section of solder ball



SEM of solder ball cross-section


X-ray